

BOARD CHARACTERISTICS

Copper Layer Count: 4 Board Thickness: 1.5470 mm  
Board overall dimensions: 54.9766 mm x 79.9766 mm  
Min track/spacing: 0.1500 mm / 0.1500 mm Min hole diameter: 0.2000 mm  
Copper Finish: HAL lead-free Impedance Control: Yes  
Castellated pads: No Plated Board Edge: No  
Edge card connectors: No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
TopLayer_Silk.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
TopLayer_Paste.Paste	Top Solder Paste		0 mm		1	0
TopLayer_Mask.Mask	Top Solder Mask	Not specified	0.01 mm	Green	3.3	0
L1_TopLayer.Cu	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.1785 mm	Not specified	4.56	0.02
L2_InnerLayer1.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.03 mm	Not specified	4.6	0.02
L3_InnerLayer1.Cu	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.1785 mm	Not specified	4.56	0.02
L4_BottomLayer.Cu	copper		0.035 mm		1	0
BottomLayer_Mask.Mask	Bottom Solder Mask	Not specified	0.01 mm	Green	3.3	0
BottomLayer_Paste.Paste	Bottom Solder Paste		0 mm		1	0
BottomLayer_Silk.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

SJFOM

Sheet: Black-And-White-TOP  
File: StepUp.kicad\_pcb

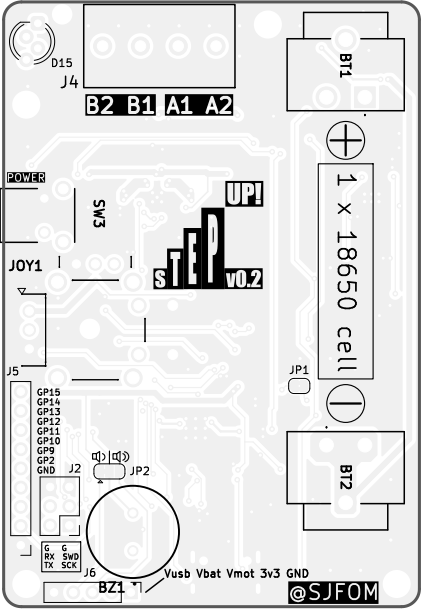
Title: StepUp

Size: A4 Date: 2024-05-06

KiCad E.D.A. 8.0.6

Rev: v0.2

Id: 1/1



BOARD CHARACTERISTICS

Edge card connectors:	No	Castled pads:	No	Copper Finish:	HAL lead-free	Impedance Control:	Yes	Min hole diameter:	0.5000 mm	Board overall dimensions:	54.9766 mm x 79.9766 mm	Copper Layer Count:	4	Board Thickness:	1.2470 mm
-----------------------	----	---------------	----	----------------	---------------	--------------------	-----	--------------------	-----------	---------------------------	-------------------------	---------------------	---	------------------	-----------

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
BottomLayer_Silk_Screen	Bottom Silk Screen	Not specified	0 mm	White	1	0
BottomLayer_Paste_Paste	Bottom Solder Paste	0 mm			1	0
BottomLayer_Mask_Mask	Bottom Solder Mask	Not specified	0.01 mm	Green	3.3	0
LT_TopLayer_Cu	Copper		0.035 mm		1	0
Dielectric	Dielectric	FR4	0.1785 mm	Not specified	4.5	0.05
LT_InnerLayer1_Cu	Copper		0.035 mm		1	0
Dielectric	Dielectric	FR4	0.13 mm	Not specified	4.5	0.05
LT_InnerLayer1_Cu	Copper		0.035 mm		1	0
Dielectric	Dielectric	FR4	0.1785 mm	Not specified	4.5	0.05
LT_BottomLayer_Cu	Copper		0.035 mm		1	0
BottomLayer_Mask_Mask	Bottom Solder Mask	Not specified	0.01 mm	Green	3.3	0
BottomLayer_Paste_Paste	Bottom Solder Paste	0 mm			1	0
BottomLayer_Silk_Screen	Bottom Silk Screen	Not specified	0 mm	White	1	0

SJFOM

Sheet: Black-And-White-BOT  
File: StepUp.kicad\_pcb

Title: StepUp

Size: A4 | Date: 2024-05-06

KiCad E.D.A. 8.0.6

Rev: v0.2

Id: 1/1